

P-Channel Enhancement Mode Power MOSFET

DESCRIPTION

The HM3401Ö uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

GENERAL FEATURES

• $V_{DS} = -30V, I_{D} = -4.6A$

 $R_{DS(ON)}$ < 100m Ω @ V_{GS} =-2.5V

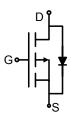
 $R_{DS(ON)} < \hat{I} 5m\Omega @ V_{GS} = -4.5V$

 $R_{DS(ON)} < 15 \text{ Sm}\Omega @ V_{GS} = -10V$

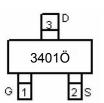
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

- PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin Assignment



SOT-23-3L top view

Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
3401Ö	HM3401Ö	SOT-23-3L	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (TA=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _G S	±12	V
Drain Current-Continuous	I _D	-4.Î	Α
Drain Current-Pulsed (Note 1)	I _{DM}	-3G	Α
Maximum Power Dissipation	P _D	1.2	W
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	104	°C/W
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Electrical Characteristics (TA=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30		-	٧
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-24V,V _{GS} =0V	-	-	-1	μΑ





Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-0.Î	-€È	-Œ	V	
		V _{GS} =-10V, I _D =-4.Î A	-	50	55	mΩ	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-4A	-	6€	îí	mΩ	
		V _{GS} =-2.5V, I _D =-1A		95	120	mΩ	
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-4.6A	-	10	-	S	
Dynamic Characteristics (Note4)	·						
Input Capacitance	C _{lss}	\/ - 45\/\/ -0\/	-	950	-	PF	
Output Capacitance	C _{oss}	V_{DS} =-15V, V_{GS} =0V, F=1.0MHz	-	115	-	PF	
Reverse Transfer Capacitance	C _{rss}	F = 1.0IVII 12	-	75	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t _{d(on)}		-	7	-	nS	
Turn-on Rise Time	t _r	V _{DD} =-15V,I _D =-3.2A	-	3	-	nS	
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10 V , R_{GEN} =6 Ω	-	30	-	nS	
Turn-Off Fall Time	t _f		-	12	-	nS	
Total Gate Charge	Qg		-	9.5	-	nC	
Gate-Source Charge	Q_{gs}	V_{DS} =-15V, I_{D} =-4A, V_{GS} =-4.5V	-	2	-	nC	
Gate-Drain Charge	Q _{gd}		-	3	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-1A	-	-	-1.2	V	

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

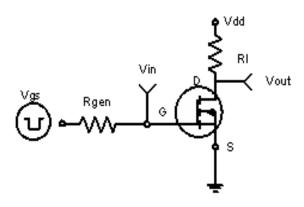
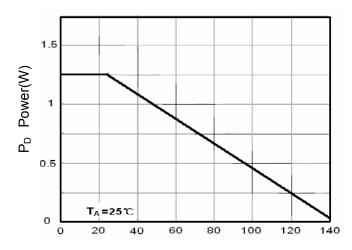
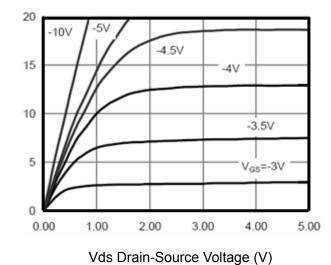


Figure 1:Switching Test Circuit



 T_J -Junction Temperature(${}^{\circ}$ C) Figure 3 Power Dissipation



I_D- Drain Current (A)

Figure 5 Output CHARACTERISTICS

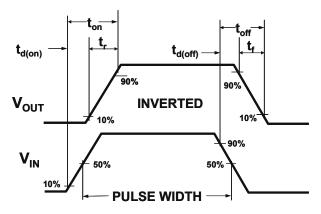


Figure 2:Switching Waveforms

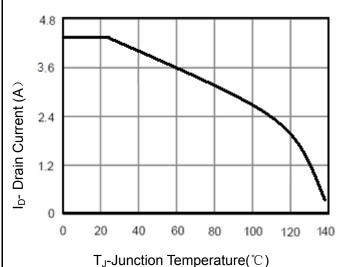


Figure 4 Drain Current

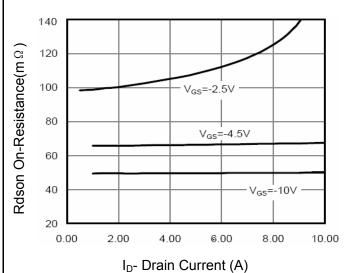


Figure 6 Drain-Source On-Resistance

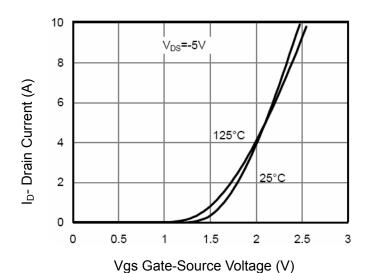
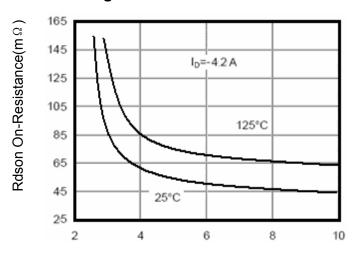


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

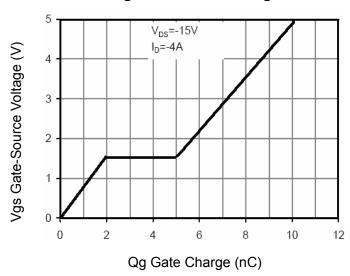
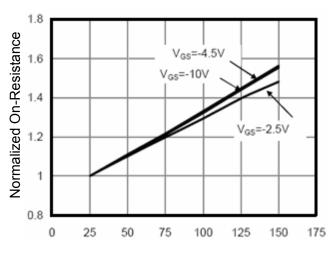
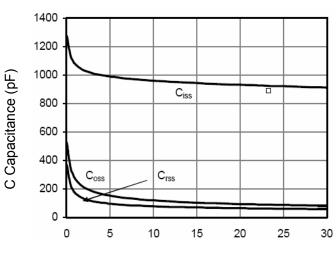


Figure 11 Gate Charge



T_J-Junction Temperature(°C)





Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds

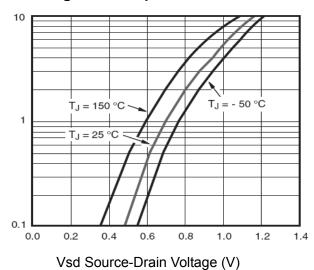
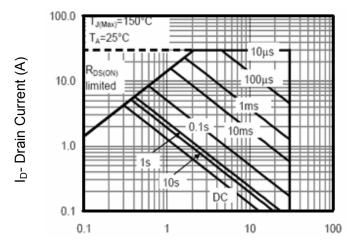


Figure 12 Source- Drain Diode Forward

Is- Reverse Drain Current (A)



Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area

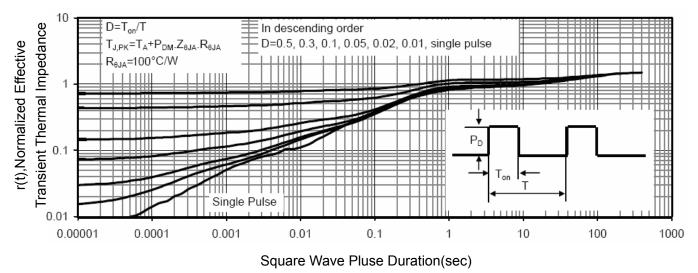
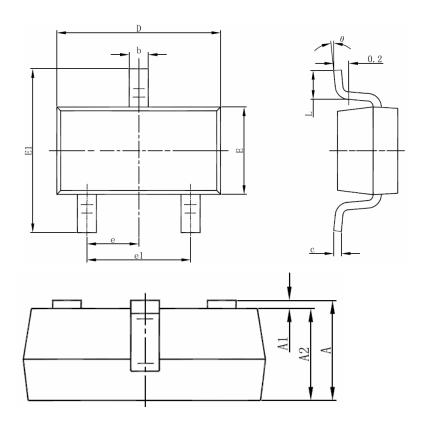


Figure 14 Normalized Maximum Transient Thermal Impedance

SOT-23-3L PACKAGE INFORMATION



Country of	Dimensions In	Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950	(BSC)	0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
Ĺ	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

NOTES

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

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